No. of Questions: 6
Enr
Faculty of End Sem Exam EC3CO12 Programme: B.Tech.
on: 3 Hrs.
All questions are compulsory. Internal choice CQs) should be written in full instead of only ary. Notations and symbols have their usual n
In MOSFET devices the N-channel type type in the following respect- (a) It has better immunity (b) It is Fast (c) It is TTL compatible (d) It has better implement (a) 3 (b) 4 (c) 5 i. In the CMOS inverter circuit if the transmostation and PMOS transistor μpCoxWp/Lp= 40 μA /V² and thresh VGS=2.5V, VDD=5 V then the current ID is (a) 0 A (b)25 μA (c) 45 μA (d) In CMOS circuits, which type of power switching of transient current and chancapacitance? (a) Static dissipation (b) Dynam (c) Both (a) and (b) (d) Open Compatible (d) Open Compatible (d) Inputs (e) Next state (e) Output in a sequence detector, if the required bit the sequence bit by bit, the detector move (a) Previous state (b) Next state (b) Next state (c) Output in the sequence bit by bit, the detector move (a) Previous state (b) Next state (c) Output in the sequence bit by bit, the detector move (a) Previous state (b) Next state (c) Output in the sequence bit by bit, the detector move (a) Previous state (b) Next state (c) Output in the sequence bit by bit, the detector move (a) Previous state (b) Next state (c) Output in the sequence bit by bit, the detector move (a) Previous state (b) Next state (c) Output in the sequence bit by bit, the detector move (a) Previous state (b) Next state (c) Output in the sequence of the sequence
(c) present state (d) Null statistic. If there are 7 states in any sequential circontain squares(cells). (a) 10 (b) 11 (c) 21

Total No. of Printed Pages:3

Enrollment No.....

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Branch/Specialisation: EC

Maximum Marks: 60

ernal choices, if any, are indicated. Answers of ta if

_		Qs) should be written in full instead of only a, b, c or d. Assume suitable da . Notations and symbols have their usual meaning.	ιt
Q.1	i.	In MOSFET devices the N-channel type is better than the P – Channel type in the following respect-	-
		(a) It has better immunity (b) It is Faster	
		(c) It is TTL compatible (d) It has better drive capability	
	ii.	How many TG are required to implement 4 x 1 mux?	-
		(a) 3 (b) 4 (c) 5 (d) 6	
	iii.	In the CMOS inverter circuit if the transconductance parameters of	-
		NMOS and PMOS transistor are $Kn=Kp=\mu nCoxWn/Ln=$	
		$\mu p CoxWp/Lp = 40 \mu A /V^2$ and threshold voltages are $VT = 1V$,	
		V_{GS} =2.5V, V_{DD} =5 V then the current I_D is-	
		(a) $0 A$ (b) $25 \mu A$ (c) $45 \mu A$ (d) $90 \mu A$	
	iv.	In CMOS circuits, which type of power dissipation occurs due to	
		switching of transient current and charging & discharging of load	
		capacitance?	
		(a) Static dissipation (b) Dynamic dissipation	
		(c) Both (a) and (b) (d) Open Circuit dissipation	
	v.	Two states are said to be equivalent states if they have exactly same-	-
		(a) Inputs (b) Next state (c) Output (d) Both (b) and (c)	
	vi.	In a sequence detector, if the required bit is at its input while checking	
		the sequence bit by bit, the detector moves to-	

equential circuit, then its merger table will 1

(c) 21 (d) 20

P.T.O.

5

	viii.	When a circuit goes	through a uniq	ue sequence of	unstable states then	1
		it is called as-				
		(a) Hazards	(b) Glitch	(c) Cycle	(d) Race	
	ix.	In modern ICS	_ is used as ga	te material.		1
		(a) Polysilicon	(b) Si	(c) Cu	(d) Al	
	х.	Which gives scalable	design rules?			1
		(a) Micron rules		(b) Layer rule	S	
		(c) Thickness rules		(d) Lambda rı	ıles	
Q.2	i.	What is body effect?				2
	ii.	Explain the term pass	s transistor with	n example.		3
	iii.	Explain the operati	ion of negati	ve edge-trigge	ered register using	5
		complementary switch	ch.			
OR	iv.	Describe the equation	n for source to	drain current in	the three regions of	5
		operation of a PMOS	transistor and	draw the VI ch	aracteristics.	
2	•	D ("				_
Q.3	i.	Define rise time, fall		-		-
	ii.	What is PDP? Derive	-	•	-	7
OR	iii.	Draw and explain the				7
		necessary conditions	for the differen	nt regions of op	eration.	
2.4	•	D' 1 4	1 .		1	,
Q.4	i.	Discuss mealy to moo			•	4
	ii.	Design a sequence de		-	-	(
		and produce output	Z as 1'. R	ealize the har	dware (overlapping	
		allowed).				
ЭR	iii.	Determine the minin	nal state table	equivalent to	the following using	(

Present	Next state,	, output
State	X = 0	X = 1
A	В,0	C,1
В	A,1	E,0
С	D,0	A,1
D	C,1	E,0
Е	A,1	F,0
F	E,0	F,1

merger graph method:

Q.5	i.	What is	s fu	ından	nental ı	nod	le & pu	lse mode	operat	ion	?			2
	ii.	What	do	you	mean	by	race?	Explain	types	of	races	with	proper	3
		exampl	le.											

iii.	Find race free state a	assignm	ent for f	ollowin	ig flow t	able:
		(a)	С	đ	(a)	
		a	đ	(b)	(b)	

OR iv. What is hazard? Find the circuit that has no static hazards and 5 implement the Boolean function $F(A,B,C,D)=\sum m(1,5,6,7)$.

[3]

Q.6 Attempt any two:

- i. Explain the different steps involved in n-well CMOS fabrication 5 process with neat diagrams.
- ii. Describe architecture of FPGA.
- iii. What are layout design rules? Design the layout of CMOS inverter 5 with suitable design rules.

Scheme of Marking



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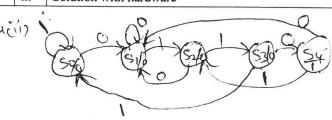
Programme: B.Tech.

Branch/Specialisation:

9/05/1

e: The Paper Setter should provide the answer wise splitting of the marks in scheme below.

1	i)	(b) It is Faster	1
	ii)	(d) 6	1
	iii)	(c) 45 µA	1
	iv)	(b) Dynamic dissipation	1
	v)	d. both b and c	1
	vi)	b. Next state	1
	vii)	(c) 21	1
	viii)	(c) cycle	1
	ix)	(a) Polysilicon	1
	x)	(d) lambda rules	1
2_	i.	definition	2
	ii.	definition .	1.5,1.5
	iii.	diagram & working	2.5,2.5
-	iv.	diagram & working	2.5,2.5
3	i.	Each definition	3
	ii.	Definition & derivation	3,4
	iii.	Characteristics & diagram with equations	3,2,2
1	i.	Conversion with example	2,2
	ii.	Solution with hardware	3,3
	*		



OR	iii.		n.c	N	S	1	Z		3,3		
		,	PS	X=0	X=1	X=0	X=1				
			A	В	A	0	1				
			В	· A	E	1	0		•		
			E	Α	\boldsymbol{F}	1	0	. *			
		$A \equiv C B \equiv D$	F	E	F	0	1				
Q.5	i.	definition							2		
	ii.	Race with exa	mpl	е					3		
	iii.	solution							5		
OR	iv.	Definition & s	olut	ion					2,3		
Q.6	-			·							
	i.	Steps & diagra	am						2,3		
	ii.	Architecture d	Architecture diagram & explanation								
	iii.	Definition &d	esig	n					2,3		

